

## LED140 Flux-P

### No-Clean Flux

#### Description

LED140 Flux-P is a no-clean tacky flux designed for mini/micro-LED transferring and soldering process, which promotes outstanding die attachment and minimizes soldering defects. The LED140 Flux-P system is specifically optimized for printing process. This formula provides superior performance on a variety of metal surface and leads to the residue transparent after soldering.

#### Key Features

- High yield for die transferring
- Excellent wetting performance and shear strength
- Best solution for mini/micro-LED application

#### Applications

- Printing

#### Flux Activity

Activity Level (J-STD 004)	ROLO
Cleaning	Solvent Clean/ No Cleaning Required

#### Halogen

Halogen content	Halogen Free
Tolerances from IEC 61249-2-21	Cl or Br <900ppm, total <1500ppm; measured according to BS EN 14582

#### Paste Preparation

Remove paste from fridge: Before opening the package, leave paste for at least 2 hours (depending on jar/cartridge size) at room temperature so that flux warms up. Do not open jar/cartridge while flux is cold to prevent condensation. Do not heat the flux beyond room temperature.

#### Cleaning Instructions

After reflow flux residues may remain on the circuit and do not need to be washed. For cleaning of wet paste or if desired for cleaning of flux residues Zestron and Vigon cleaners can be used – see separate cleaning recommendations.

#### Storage

- Store the flux in solder paste sealed cartridges and avoid exposure to sunlight and high humidity
- Max expiration date: please refer to the expiry date on the label of the packaged product
- Storage condition in the refrigerator at 2-10 °C

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